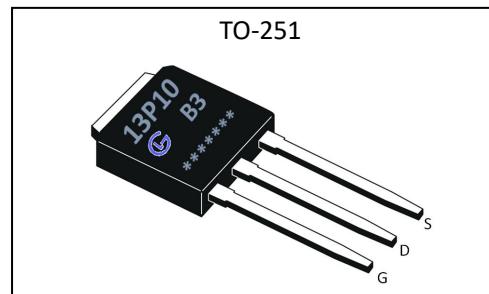


General Description:

The GL13P10B3 uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications. The package form is TO-251, which accords with the RoHS standard.

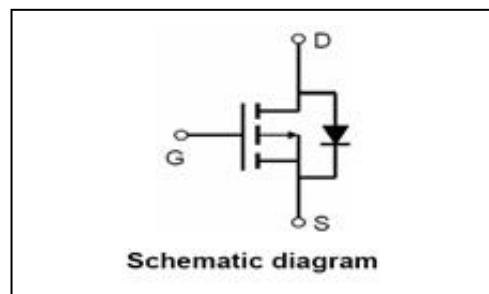
| | | |
|-------------------|------|-----------|
| V_{DSS} | -100 | V |
| I_D | -13 | A |
| P_D | 40 | W |
| $R_{DS(ON)}$ TYPE | 250 | $m\Omega$ |


Features:

- Fast Switching
- Low Gate Charge and Rdson
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

Applications:

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply


Absolute (Tc=25°C unless otherwise specified):

| Symbol | Parameter | Rating | Units |
|----------------|--|-----------------|-------|
| V_{DSS} | Drain-to-Source Voltage | -100 | V |
| I_D | Continuous Drain Current | -13 | A |
| | Continuous Drain Current $T_c = 100^\circ C$ | -9.5 | A |
| I_{DM}^{a1} | Pulsed Drain Current | -30 | A |
| V_{GS} | Gate-to-Source Voltage | ± 20 | V |
| d_v/dt^{a3} | Peak Diode Recovery dv/dt | 5.0 | V/ns |
| P_D | Power Dissipation | 40 | W |
| T_J, T_{stg} | Operating Junction and Storage Temperature Range | 150, -55 to 150 | °C |
| T_L | Maximum Temperature for Soldering | 300 | °C |



GL13P10B3

GL Silicon P-Channel Power MOSFET

Electrical Characteristics ($T_c=25^\circ C$ unless otherwise specified):

| OFF Characteristics | | | | | | |
|-----------------------------|-----------------------------------|---|--------|------|------|--------------|
| Symbol | Parameter | Test Conditions | Rating | | | Units |
| | | | Min. | Typ. | Max. | |
| V_{DSS} | Drain to Source Breakdown Voltage | $V_{GS}=0V, I_D=-250\mu A$ | -100 | -- | -- | V |
| $\Delta V_{DSS}/\Delta T_J$ | Bvdss Temperature Coefficient | $I_D=-250\mu A$, Reference $25^\circ C$ | -- | 0.15 | -- | $V/^\circ C$ |
| I_{DSS} | Drain to Source Leakage Current | $V_{DS}=-100, V_{GS}=0V, T_a=25^\circ C$ | -- | -- | -1 | μA |
| | | $V_{DS}=-80V, V_{GS}=0V, T_a=125^\circ C$ | -- | -- | -250 | |
| $I_{GSS(F)}$ | Gate to Source Forward Leakage | $V_{GS}=+20V$ | -- | -- | 10 | μA |
| $I_{GSS(R)}$ | Gate to Source Reverse Leakage | $V_{GS}=-20V$ | -- | -- | -10 | μA |

| ON Characteristics | | | | | | |
|--|-------------------------------|--------------------------------|--------|------|------|-----------|
| Symbol | Parameter | Test Conditions | Rating | | | Units |
| | | | Min. | Typ. | Max. | |
| $R_{DS(ON)}$ | Drain-to-Source On-Resistance | $V_{GS}=-10V, I_D=-13.0A$ | -- | 250 | 270 | $m\Omega$ |
| $V_{GS(TH)}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}, I_D=-250\mu A$ | -1.0 | -1.9 | -3.0 | V |
| Pulse width $t_p \leq 380\mu s, \delta \leq 2\%$ | | | | | | |

| Dynamic Characteristics | | | | | | |
|-------------------------|------------------------------|--------------------------|--------|------|------|-------|
| Symbol | Parameter | Test Conditions | Rating | | | Units |
| | | | Min. | Typ. | Max. | |
| g_{fs} | Forward Transconductance | $V_{DS}=-10V, I_D=-5A$ | 12 | 25 | -- | S |
| C_{iss} | Input Capacitance | $V_{GS}=0V, V_{DS}=-50V$ | -- | 510 | -- | pF |
| C_{oss} | Output Capacitance | $f=1.0MHz$ | -- | 170 | -- | |
| C_{rss} | Reverse Transfer Capacitance | | -- | 115 | -- | |

| Resistive Switching Characteristics | | | | | | |
|-------------------------------------|----------------------------------|---------------------------------|--------|------|------|-------|
| Symbol | Parameter | Test Conditions | Rating | | | Units |
| | | | Min. | Typ. | Max. | |
| $t_{d(ON)}$ | Turn-on Delay Time | $R_L=-1.5\Omega, V_{DD} = -50V$ | -- | 11 | -- | ns |
| t_r | Rise Time | | -- | 12 | -- | |
| $t_{d(OFF)}$ | Turn-Off Delay Time | | -- | 30 | -- | |
| t_f | Fall Time | | -- | 12 | -- | |
| Q_g | Total Gate Charge | $I_D=-10.0A, V_{DD}=-50V$ | -- | 16 | -- | nC |
| Q_{gs} | Gate to Source Charge | | -- | 4 | -- | |
| Q_{gd} | Gate to Drain ("Miller")Charge | | -- | 4.2 | -- | |

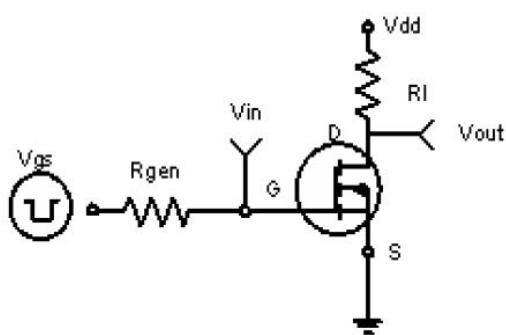
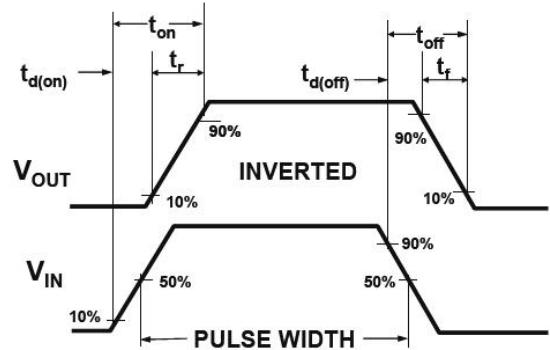
Source-Drain Diode Characteristics

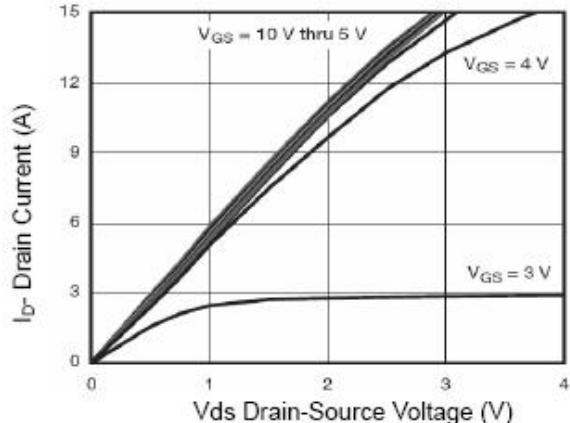
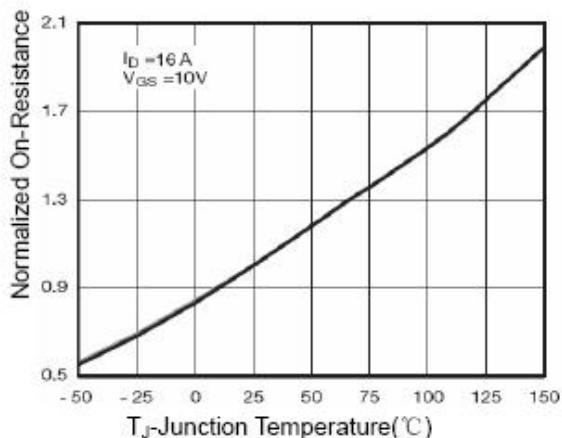
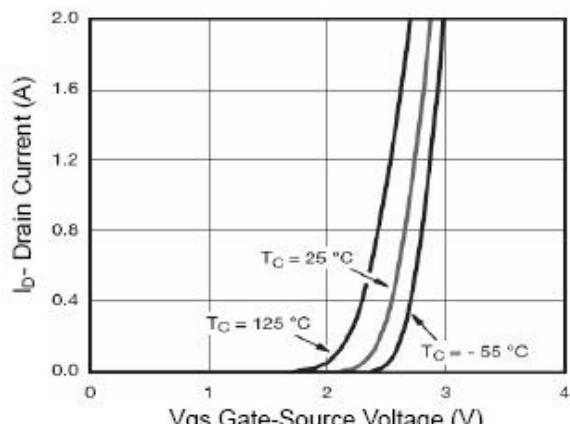
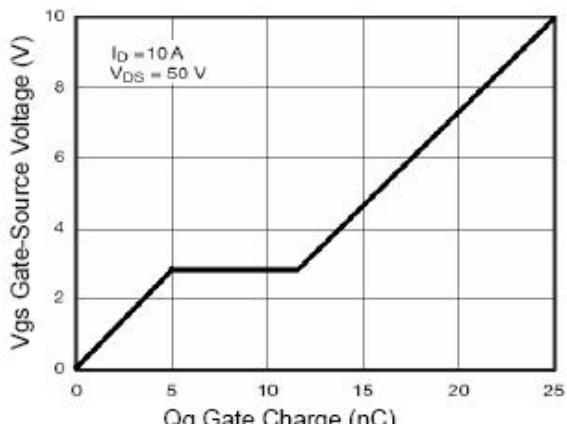
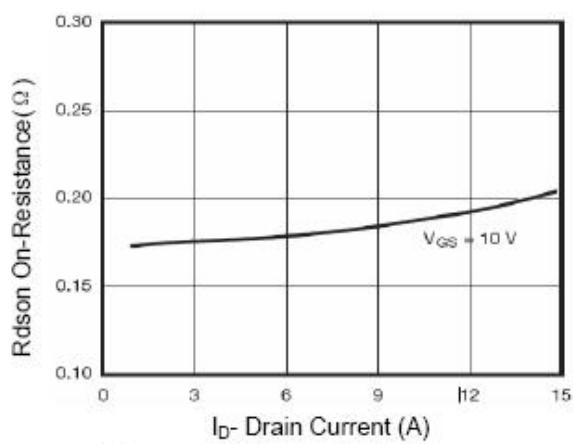
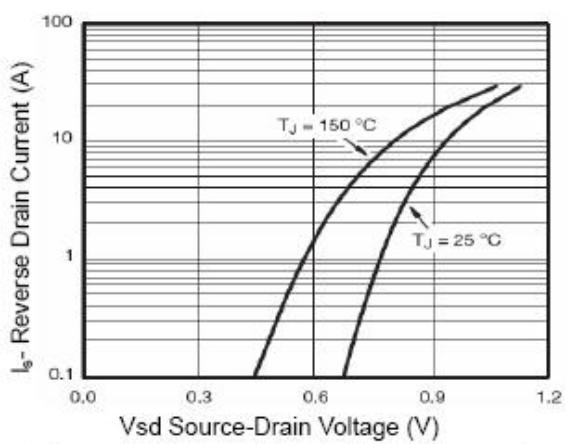
| Symbol | Parameter | Test Conditions | Rating | | | Units |
|----------|--|-------------------------------------|--------|------|------|-------|
| | | | Min. | Typ. | Max. | |
| I_S | Continuous Source Current (Body Diode) | | -- | -- | -13 | A |
| I_{SM} | Maximum Pulsed Current (Body Diode) | | -- | -- | -30 | A |
| V_{SD} | Diode Forward Voltage | $I_S = -13A, V_{GS} = 0V$ | -- | -- | 1.5 | V |
| t_{rr} | Reverse Recovery Time | $I_S = -13A, T_j = 25^\circ C$ | -- | 25 | -- | ns |
| Q_{rr} | Reverse Recovery Charge | $dI_F/dt = 100A/\mu s, V_{GS} = 0V$ | -- | 32 | -- | nC |

 Pulse width $t_p \leq 380\mu s, \delta \leq 2\%$

| Symbol | Parameter | Typ. | Units |
|-----------|------------------|------|-------|
| $R_{θJC}$ | Junction-to-case | 3.13 | °C/W |

^{a1}: Repetitive rating; pulse width limited by maximum junction temperature

^{a3}: $I_{SD} = -13A, dI/dt \leq 100A/\mu s, V_{DD} \leq BV_{DS}$, Start $T_j = 25^\circ C$
Typical Electrical and Thermal Characteristics

Figure 1:Switching Test Circuit

Figure 2:Switching Waveforms

Typical Electrical and Thermal Characteristics (Curves)

Figure 1 Output Characteristics

Figure 4 Rdson-JunctionTemperature

Figure 2 Transfer Characteristics

Figure 5 Gate Charge

Figure 3 Rdson-Drain Current

Figure 6 Source-Drain Diode Forward

